

Docket No. 0760-0296P

REMARKS

The specification has been amended to provide a cross-reference to the previously filed International Application.

Upon entry of the present amendment, claims 1-18 will remain pending in the present application. Claims 9-11, 14-16 and 18 have been amended herein to remove improper multiple dependencies.

No new matter has been added to the application as originally filed.

Entry of the above amendments is earnestly solicited. An early and favorable first action on the merits is earnestly solicited.

If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment or credit any overpayment to Deposit Account No. 02-2448 for any additional fees required under 37 C.F.R. § 1.16 or under 37 C.F.R. § 1.17; particularly, extension of time fees.

Respectfully submitted,

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By

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JWB/end
0760-0296P

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Attachment: VERSION WITH MARKINGS TO SHOW CHANGES MADE

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IN THE SPECIFICATION:

A paragraph has been added before the paragraph beginning on page 1, line 1.

IN THE CLAIMS:

The claims have been amended as follows:

9. (Amended) The composition according to [any one of claims 1-8] claim 1, wherein said polyimide has an average molecular weight in terms of polystyrene of 5000 to 100,000.

10. (Amended) The composition according to [any one of claims 1-9] claim 1, wherein said polyimide does not substantially comprise conjugated double bond and aromatic structure.

11. (Amended) A method for forming polyimide pattern comprising irradiating said polyimide recited in [any one of claims 1 to 10] claim 1 with a light in the presence of a photoacid generator, which polyimide is in the form of a thin film coating a substrate; and removing the irradiated regions with an alkaline developing solution.

14. (Amended) A method for forming a pattern of positive-type photosensitive polyimide comprising the steps of forming a photosensitive layer consisting essentially of said polyimide composition according to [any one of claims 1 to 10] claim 1 on a substrate; selectively irradiating said photosensitive layer with a light beam having a wavelength of not more than 365 nm; heat-treating said photosensitive layer; and developing said photosensitive layer after said heat-treatment to selectively remove prescribed regions in said photosensitive layer.

15. (Amended) Use of said polyimide recited in [any one of claims 1 to 10] claim 1 as a material for positive-type photolithography.

16. (Amended) A method for forming negative-type pattern of polyimide comprising coating a substrate with the polyimide recited in [any one of claims 1 to 10] claim 1; selectively irradiating the polyimide with an actinic ray, the irradiated regions constituting a desired pattern; and developing the irradiated polyimide with an alkaline solution to dissolve the non-irradiated regions.

18. (Amended) Use of the polyimide recited in [any one of claims 1 to 10] claim 1 as a material for negative-type photolithography.